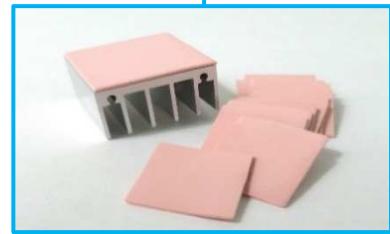


GAP PAD

Our Thermal Foams also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that solve the problems of heat dissipation. The TGF_013_DXS_(GF) is a fiberglass mattress specially developed for applications where a low cooling requirement is required. Indeed, it is a good thermal conductor of 1.3W/ mK, with good thermal resistance thus facilitating the transfer of heat and also has excellent electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

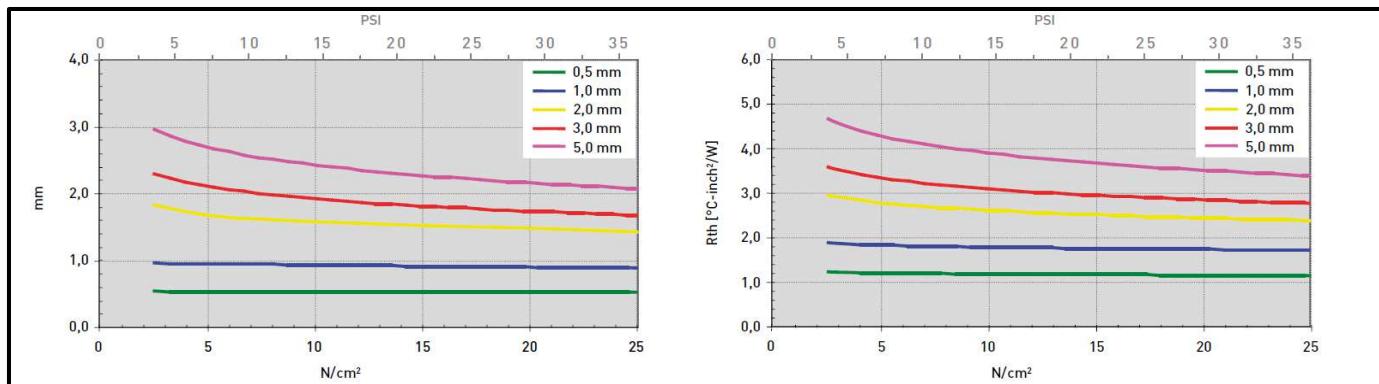


Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

Technical characteristics

Caractéristiques	Unit	TGF_013_DXS			
Thickness	mm	1	2	3	5
Reinforcement	-	Fiberglass			
Color	-	White / Pink			
Hardness	Shore 00	25			
Size	mm	200*400			
Resistance @35 Psi	°C-inch ² /W (mm)	1.77 (0.94)	2.43 (1.40)	2.80 (1.65)	3.40 (2.10)
Resistance @15 Psi		1.85 (0.95)	2.70 (1.60)	3.10 (1.95)	3.95 (2.55)
Resistance @7 Psi		1.86 (0.97)	2.80 (1.70)	3.30 (2.20)	4.40 (2.70)
Thermal conductivity	W/mK	1.3			
Temperature	°C	-40 to 180			
Breakdown voltage	kV/mm	6			
Volume resistance	0hm - cm	6.2 x 10 ¹⁵			
Contante dielectric	@1MHz	5.27			

The TGF_013_DXS_GF is available in 1/2/3/4/5/6/7/8/9/10mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.